



# Product Data Sheet – QFN

**Package Materials:**

Plastic Body: Semiconductor grade plastic, black  
Dielectric Constant = 4.4 at 1MHz

**Lead Frame:**

194 Copper (Cu) FH

**Distance from Lead frame (Die Pad) to Bonding Lead:**

4mm package - .160mm  
5mm package - .164mm  
7mm package - .160mm  
8mm package - .174mm

**Plating:**

50μ Au over 30μ Ni

PACKAGE	INDUCTANCE (Nh)	CAPACITANCE (Pf)	RESISTANCE (M-OHMS)	THETA J °C/W
4x4	.691	.251	32	35.3 TYP.
5x5	.865	.289	44	34.8 TYP.
7x7	1.37	.416	56	24.4 TYP.
8x8	1.47	.475	63	20.9 TYP.

The above data is for reference only. Spectrum recommends that customers evaluate these packages in their facility for their specific application.

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